

Features

- Enhancement mode
- Low on-resistance $R_{DS(on)}$ @ $V_{GS}=10V$
- Super Junction Technology
- ESD Protection HBM 8KV
- Pb-free lead plating; RoHS compliant; Halogen free

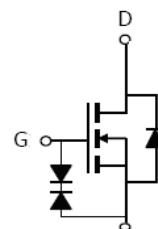

Halogen-Free

V_{DS}	700	V
$R_{DS(on),TYP}$ @ $V_{GS}=10V$	150	mΩ
I_D	20	A

TO-220WF



Part ID	Package Type	Marking	Tube Information
VSF190N70HS2	TO-220WF	190N70H	50pcs/Tube



Maximum ratings, at $T_A = 25^\circ C$, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	700	V
V_{GS}	Gate-Source voltage	± 30	V
I_S	Diode continuous forward current	$T_C = 25^\circ C$	A
I_D	Continuous drain current @ $V_{GS}=10V$	$T_C = 25^\circ C$	A
		$T_C = 100^\circ C$	A
I_{DM}	Pulse drain current tested ①	$T_C = 25^\circ C$	A
EAS	Avalanche energy, single pulsed ②	640	mJ
P_D	Maximum power dissipation	$T_C = 25^\circ C$	W
		$T_C = 100^\circ C$	W
T_{STG}, T_J	Storage and Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	4.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ $T_j = 25^\circ C$ (unless otherwise stated)						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	700	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=700V, V_{GS}=0V$	--	--	1	μA
	Zero Gate Voltage Drain Current($T_j=125^\circ C$)	$V_{DS}=560V, V_{GS}=0V$	--	--	50	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 30V, V_{DS}=0V$	--	--	± 5	μA
$V_{GS(TH)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	3.0	--	4.3	V
$R_{DS(ON)}$	Drain-Source On-State Resistance ③	$V_{GS}=10V, I_D=10A$	--	150	190	$m\Omega$
		$T_j=100^\circ C$	--	230	--	$m\Omega$
Dynamic Electrical Characteristics @ $T_j = 25^\circ C$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{DS}=30V, V_{GS}=0V, f=1MHz$	1570	1850	2130	pF
C_{oss}	Output Capacitance		725	855	985	pF
C_{rss}	Reverse Transfer Capacitance		25	35	45	pF
Q_g	Total Gate Charge	$V_{DS}=350V, I_D=10A, V_{GS}=10V$	--	39	--	nC
Q_{gs}	Gate-Source Charge		--	11	--	nC
Q_{gd}	Gate-Drain Charge		--	14	--	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=350V, I_D=10A, R_G=10\Omega, V_{GS}=10V$	--	39	--	ns
t_r	Turn-on Rise Time		--	32	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	121	--	ns
t_f	Turn-Off Fall Time		--	29	--	ns
Source- Drain Diode Characteristics@ $T_j = 25^\circ C$ (unless otherwise stated)						
V_{SD}	Forward on voltage	$I_{SD}=10A, V_{GS}=0V$	--	0.9	1.2	V
t_{rr}	Reverse Recovery Time	$T_j=25^\circ C, I_{SD}=10A, V_{GS}=0V, di/dt=100A/\mu s$	--	280	--	ns
Q_{rr}	Reverse Recovery Charge		--	3.7	--	μC

NOTE: ① Repetitive rating; pulse width limited by max junction temperature.

② Limited by T_{Jmax} , starting $T_j = 25^\circ C$, $L = 26mH$, $R_G = 25\Omega$, $I_{AS} = 7A$, $V_{GS} = 10V$. Part not recommended for use above this value.

③ Pulse width $\leq 380\mu s$; duty cycles $\leq 2\%$.



Typical Characteristics

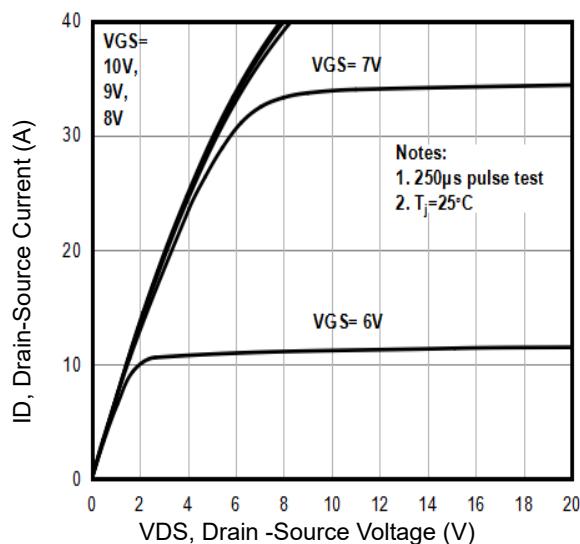


Fig1. Typical Output Characteristics

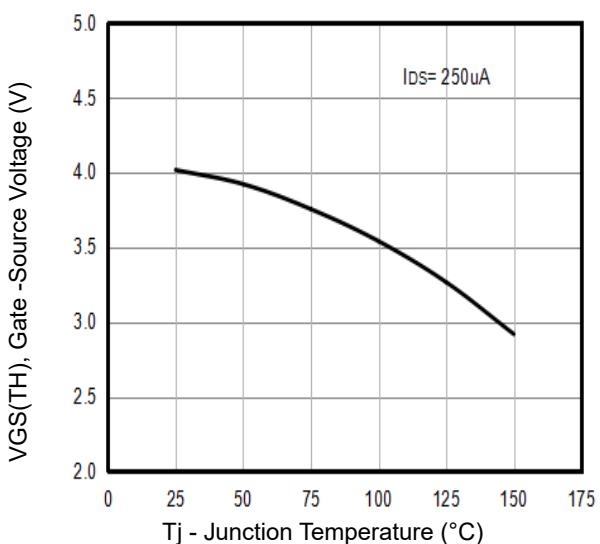


Fig2. $V_{GS(TH)}$ Gate -Source Voltage Vs. T_j

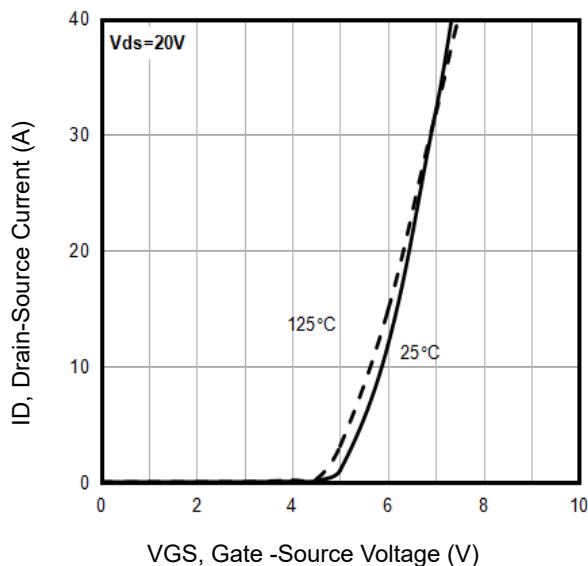


Fig3. Typical Transfer Characteristics

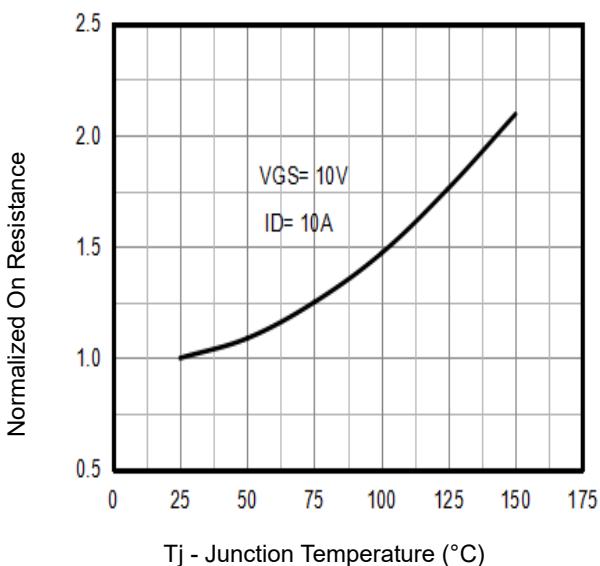


Fig4. Normalized On-Resistance Vs. Temperature

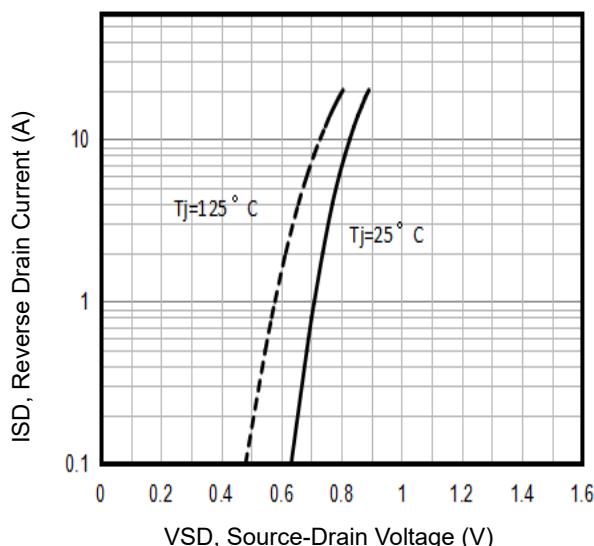


Fig5. Typical Source-Drain Diode Forward Voltage

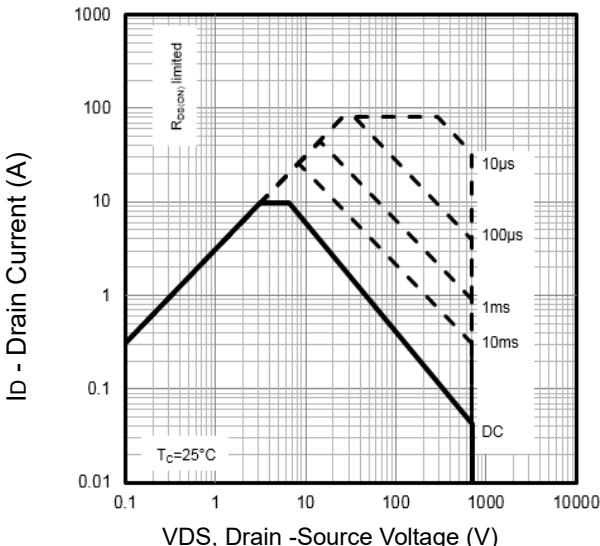


Fig6. Maximum Safe Operating Area



Typical Characteristics

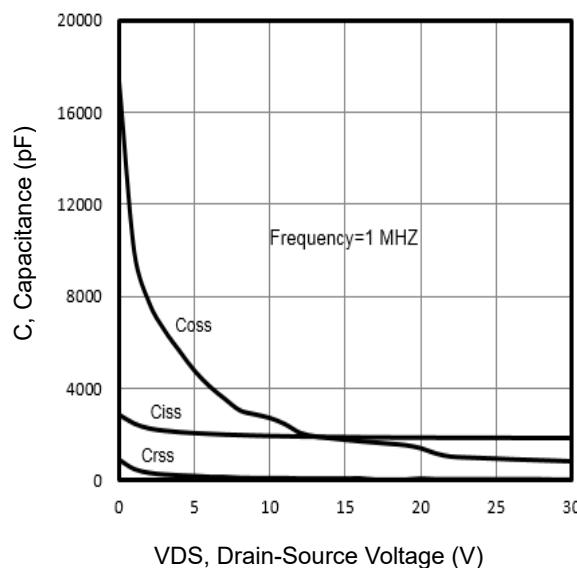


Fig7. Typical Capacitance Vs. Drain-Source Voltage

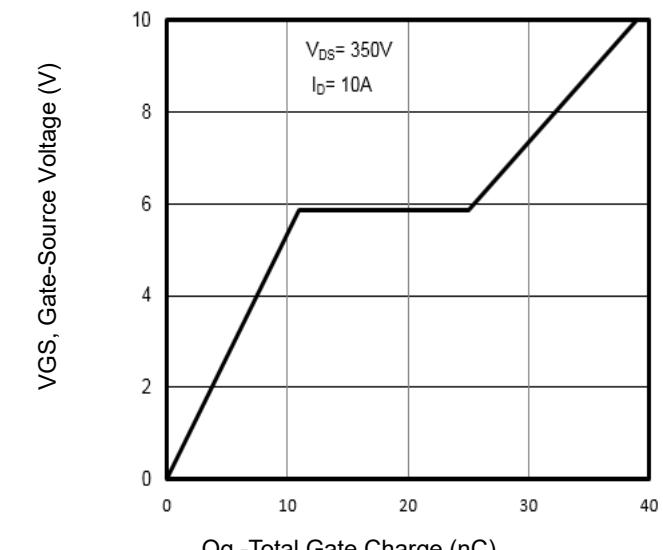


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

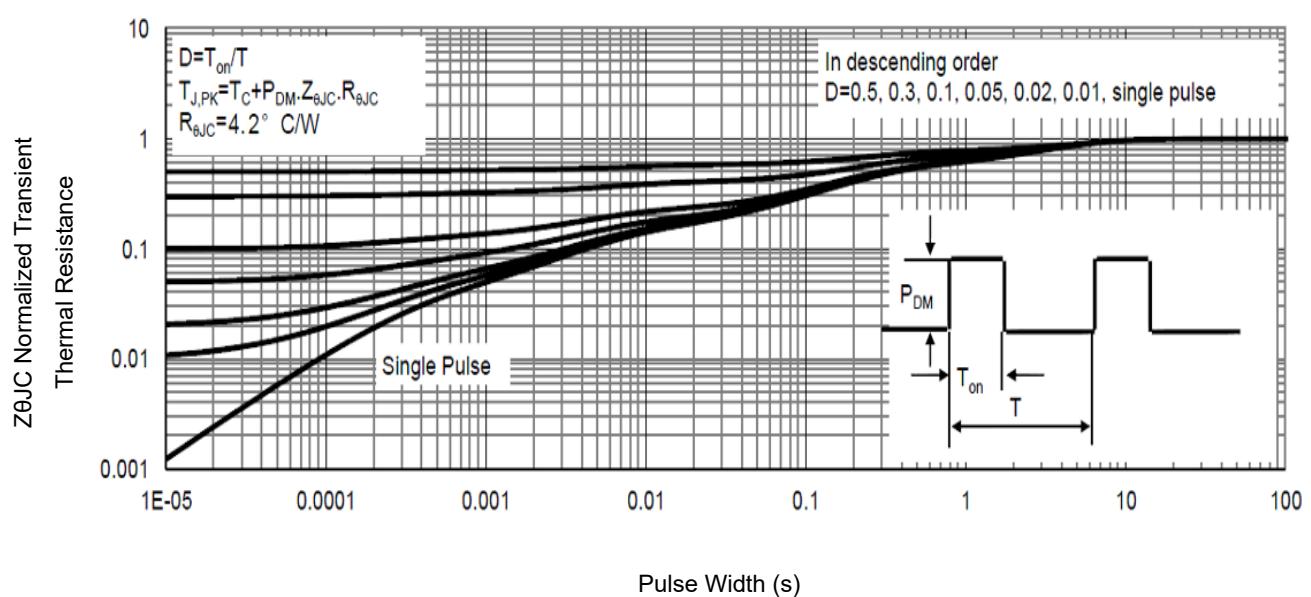


Fig9. Normalized Maximum Transient Thermal Impedance

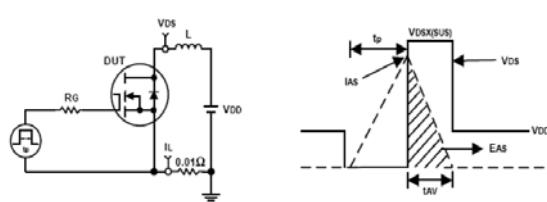


Fig10. Unclamped Inductive Test Circuit and waveforms

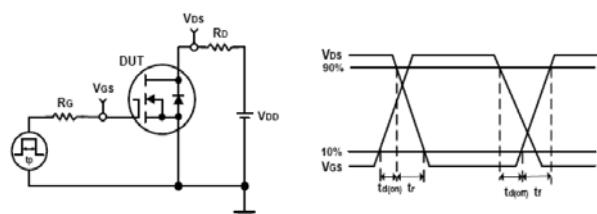
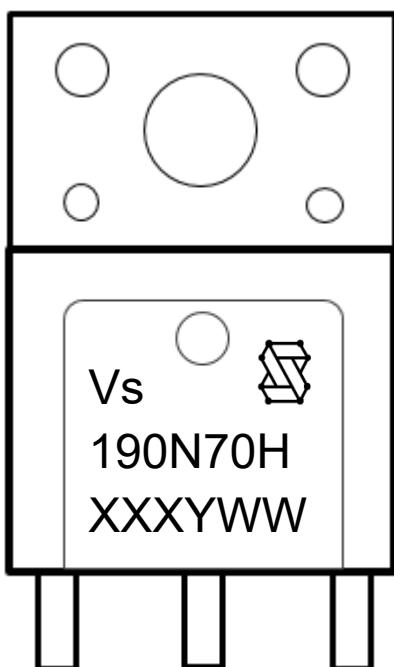


Fig11. Switching Time Test Circuit and waveforms

Marking Information



1st line: Vanguard Code (Vs), Vanguard Logo

2nd line: Part Number (190N70H)

3rd line: Date code (XXXYWW)

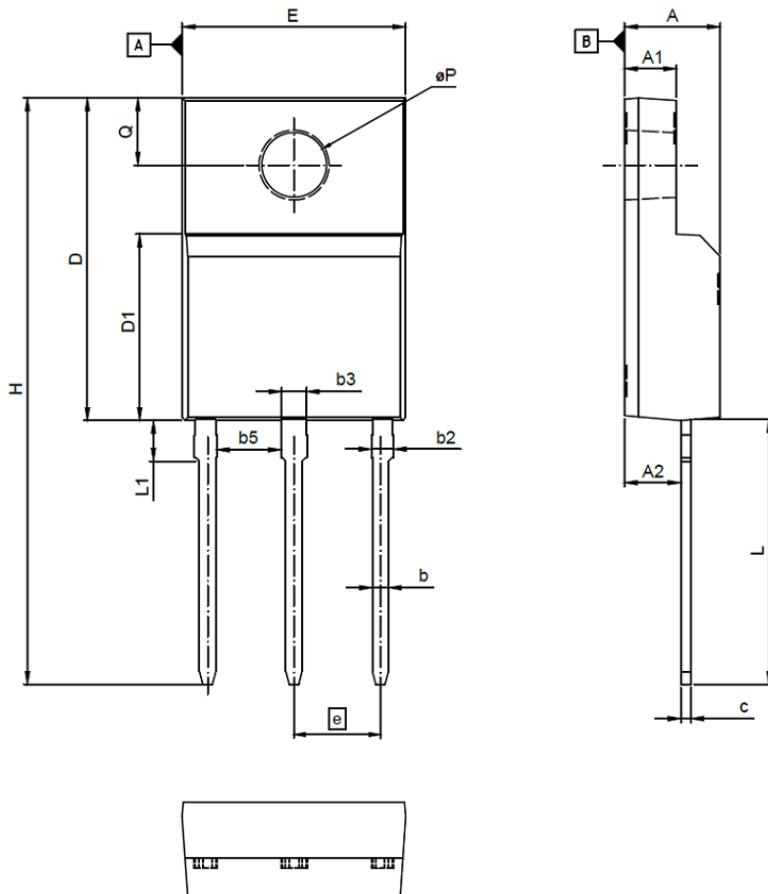
XXX: Wafer Lot Number Code , code changed with Lot Number

Y: Year Code, (e.g. E=2017, F=2018, G=2019, H=2020, etc)

WW: Week Code (01 to 53)



TO-220WF Package Outline Data



Symbol	Dimensions (unit: mm)		
	Min	Typ	Max
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A2	2.65	2.76	2.95
b	0.75	0.80	0.90
b2	0.98	1.08	1.26
b3	1.00	1.20	1.40
b5	3.00	--	--
c	0.40	0.50	0.60
D	15.47	15.87	16.27
D1	--	9.17	--
E	10.70	11.00	11.30
e	3.95	4.25	4.55
H	28.25	28.85	29.45
L	12.58	12.98	13.38
L1	1.70	2.00	2.30
φP	2.98	3.18	3.38
Q	3.10	3.30	3.50

Note:

1. Dimensions do NOT include mold flash, protrusions or gate burrs.

Customer Service

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